SDAS228A - JUNE 1982 - REVISED JANUARY 1995

- Compare Two 8-Bit Words
- Totem-Pole Outputs (P = Q)
- 'ALS688 Are Identical to 'ALS521
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

These identity comparators perform comparisons on two 8-bit binary or BCD words and provide $\overline{P} = \overline{Q}$ outputs. These devices have totem-pole outputs.

The SN54ALS688 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS688 is characterized for operation from 0°C to 70°C.

	FUNCTION TABLE										
IN	PUTS	OUTDUT									
DATA P, Q	ENABLE G	O <u>UTPU</u> T P = Q									
P = Q	L	L									
P > Q	L	н									
P < Q	L	н									
Х	Н	Н									

SN54ALS688 J PACKAGE I74ALS688 DW OR N PACKAGE (TOP VIEW)										
ਰ		20	Vcc							
P0 🛛	2	19	P = Q							
Q0 [3	18	Q7							
P1 []	4	17	P7							
Q1 [5	16	Q6							
P2 [6	15	P6							
Q2 [7	14	Q5							
P3 [8	13	P5							

SN

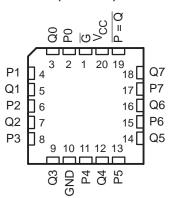
SN54ALS688 . . . FK PACKAGE (TOP VIEW)

12 🛛 Q4

11 **1** P4

Q3 🛛 9

GND 10

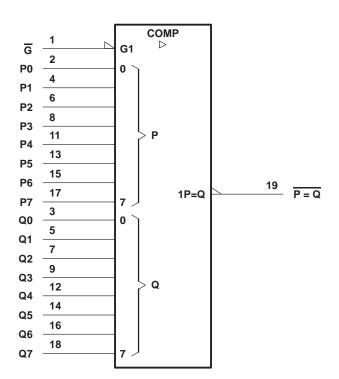


PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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logic symbol[†]

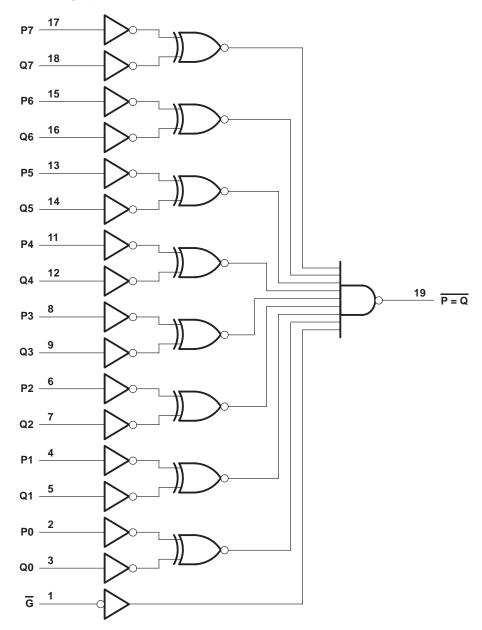


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V _I	
Operating free-air temperature range, T _A : SN54ALS688	-55°C to 125°C
SN74ALS688	0°C to 70°C
Storage temperature range	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



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recommended operating conditions

		SN	SN54ALS688			SN74ALS688			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
IOH	High-level output current			-1			-2.6	mA	
IOL	Low-level output current			12			24	mA	
TA	Operating free-air temperature	-55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST	TEST CONDITIONS			88	SN	UNIT		
PARAMETER	TESTC				MAX	MIN	TYP [†]	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = -18 mA			-1.5			-1.5	V
	V_{CC} = 4.5 V to 5.5 V,	I _{OH} = - 0.4 mA	VCC-2	2		V _{CC} -2	2		
VOH	V _{CC} = 4.5 V	I _{OH} = – 1 mA	2.4	3.3					V
	VCC = 4.5 V	I _{OH} = – 2.6 mA				2.4	3.3		
	V _{CC} = 4.5 V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VOL	VCC = 4.3 V	I _{OL} = 24 mA					0.35	0.5	v
lj	$V_{CC} = 5.5 V,$	$V_{I} = 7 V$			0.1			0.1	mA
Ιн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
۱ _{IL}	V _{CC} = 5.5 V,	$V_{ } = 0.4 V$			-0.1			-0.1	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V,	See Note 1		12	19		12	19	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}. NOTE 1: I_{CC} is measured with \overline{G} grounded, P and Q at 4.5 V.

switching characteristics (see Figure 1)

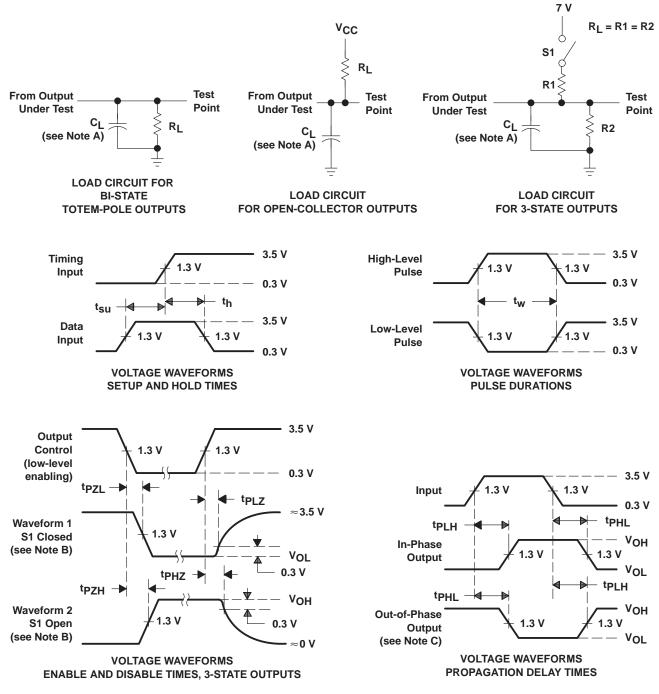
PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL RL	= 50 pF = 500 9 = MIN t	2, o MAX§		UNIT
			MIN	MAX	MIN	MAX	
^t PLH	5	<u> </u>	3	16	3	12	
^t PHL	Р	P = Q	5	25	5	20	ns
^t PLH	0	$\overline{P} = Q$	3	16	3	12	
^t PHL	Q	P=Q	5	25	5	20	ns
^t PLH	G	$\overline{P = Q}$	3	15	3	12	ns
^t PHL	5	1=0	5	25	5	22	115

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{f} = t_{f} = 2 ns, duty cycle = 50\%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-88578012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK	Samples
5962-8857801RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J	Samples
5962-8857801SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W	Samples
SN54ALS688J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS688J	Samples
SN74ALS688DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688	Samples
SN74ALS688N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS688N	Samples
SN74ALS688NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688	Samples
SNJ54ALS688FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK	Samples
SNJ54ALS688J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J	Samples
SNJ54ALS688W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.



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PACKAGE OPTION ADDENDUM

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS688, SN74ALS688 :

• Catalog : SN74ALS688

• Military : SN54ALS688

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

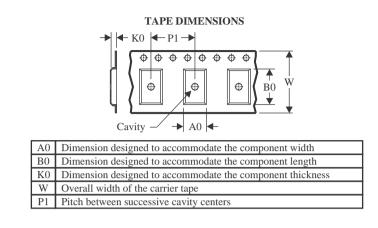


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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	-	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS688DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS688NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

16-Apr-2024



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS688DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS688NSR	SO	NS	20	2000	367.0	367.0	45.0

TEXAS INSTRUMENTS

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16-Apr-2024

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-88578012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8857801SA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ALS688N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ALS688FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS688W	W	CFP	20	25	506.98	26.16	6220	NA

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



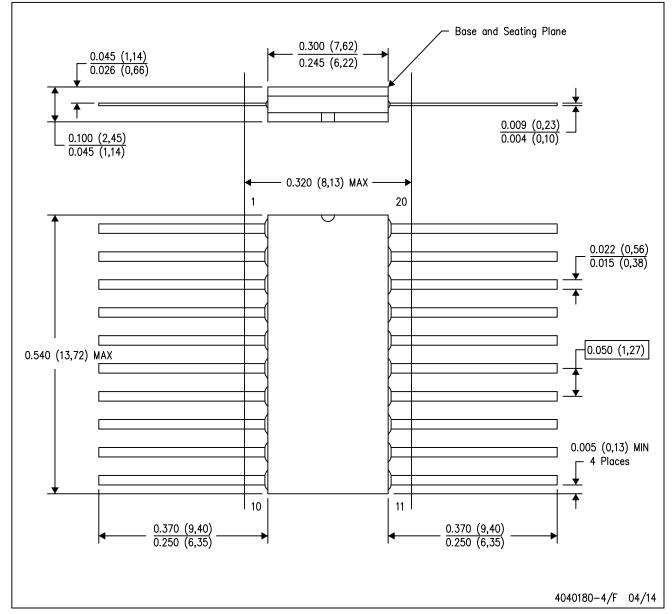
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice. В.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within Mil-Std 1835 GDFP2-F20



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